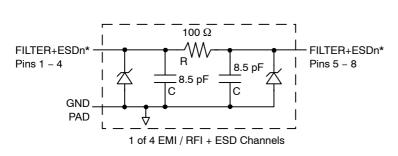
4-Channel LCD and Camera EMI Filter Array with ESD Protection

Features

- Four Channels of EMI Filtering with Integrated ESD Protection
- Pi-Style EMI Filters in a Capacitor-Resistor-Capacitor (C-R-C) Network
- ±15 kV ESD Protection on Each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- ±30 kV ESD Protection on Each Channel (HBM)
- Greater than -35 dB Attenuation (Typical) at 1 GHz
- WDFN Packaging with 0.5 mm Lead Pitch:
 - 8-Lead WDFN, 2.0 mm x 2.0 mm
- Increased Robustness Against Vertical Impacts During Manufacturing Process
- These Devices are Pb-Free and are RoHS Compliant

Applications

- LCD and Camera Data Lines in Mobile Handsets
- I/O Port Protection for Mobile Handsets, Notebook Computers, PDAs, etc.
- EMI Filtering for Data Ports in Cell Phones, PDAs or Notebook Computers
- Wireless Handsets
- Handheld PCs/PDAs
- LCD and Camera Modules



BLOCK DIAGRAM

*See Package/Pinout Diagrams for expanded pin information.



ON Semiconductor®

http://onsemi.com



MARKING DIAGRAM



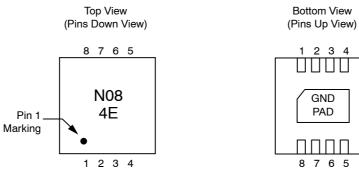
N08 4E = CM1408-04DE

ORDERING INFORMATION

Device	Package	Shipping [†]
CM1408-04DE	WDFN-8 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

PACKAGE / PINOUT DIAGRAMS



8 Lead WDFN Package

Table 1. PIN DESCRIPTIONS

Device Pin(s)	Name	Description	Device Pin(s)	Name	Description
1	FILTER1	Filter + ESD Channel 1	8	FILTER1	Filter + ESD Channel 1
2	FILTER2	Filter + ESD Channel 2	7	FILTER2	Filter + ESD Channel 2
3	FILTER3	Filter + ESD Channel 3	6	FILTER3	Filter + ESD Channel 3
4	FILTER4	Filter + ESD Channel 4	5	FILTER4	Filter + ESD Channel 4
GND PAD	GND	Device Ground			

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
DC Power per Resistor	100	mW
DC Package Power Rating	500	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

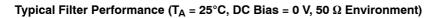
Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

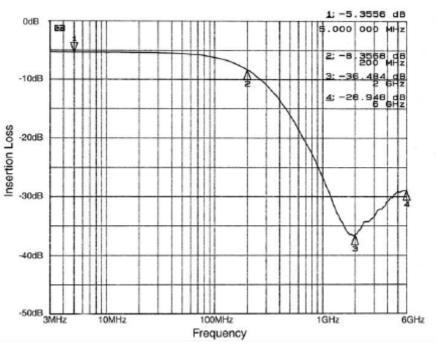
Symbol	Parameter	Conditions	Min	Тур	Max	Units
R	Resistance		80	100	120	Ω
C _{TOTAL}	Total Channel Capacitance	At 2.5 VDC Reverse Bias, 1 MHz, 30 mVAC	14	17	22	pF
С	Capacitance C	At 2.5 VDC Reverse Bias, 1 MHz, 30 mVAC		8.5		pF
V _{DIODE}	Standoff Voltage	I _{DIODE} = 10 μA		6.0		V
I _{LEAK}	Diode Leakage Current (reverse bias)	V _{DIODE} = 3.3 V		0.1	1.0	μA
V _{SIG}	Signal Clamp Voltage Positive Clamp Negative Clamp	I _{LOAD} = 10 mA I _{LOAD} = -10 mA	5.6 -1.5	6.8 -0.8	9.0 -0.4	V
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	(Notes 2 and 3)	30 15			kV
R _{DYN}	Dynamic Resistance Positive Negative			2.3 0.9		Ω
f _C	Cut–off Frequency Z_{SOURCE} = 50 Ω , Z_{LOAD} = 50 Ω	Channel R = 100 Ω, Channel C _{SINGLE} = 8.5 pF		200		MHz

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

T_A = 25°C unless otherwise specified.
 ESD applied to input and output pins with respect to GND, one at a time.
 These parameters are guaranteed by design and characterization.

PERFORMANCE INFORMATION







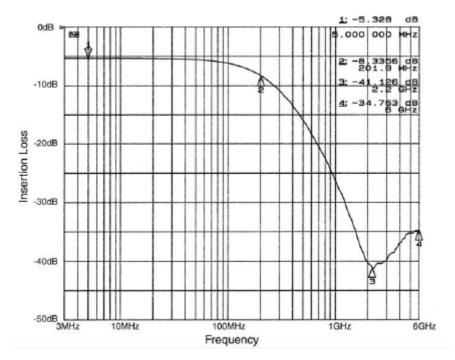
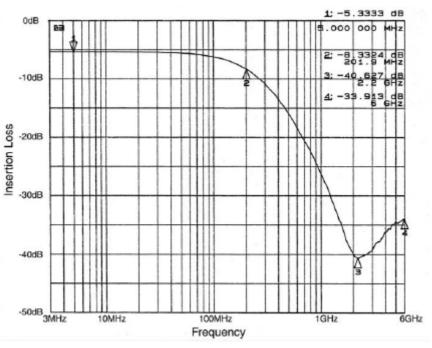


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND)

PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance (T_A = 25°C, DC Bias = 0 V, 50 Ω Environment)





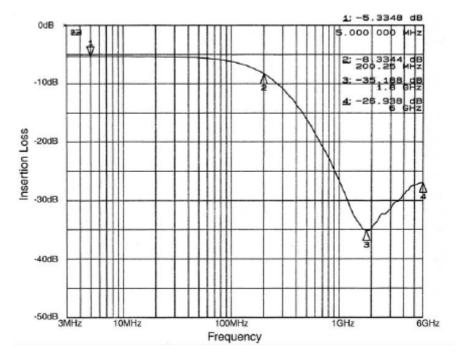
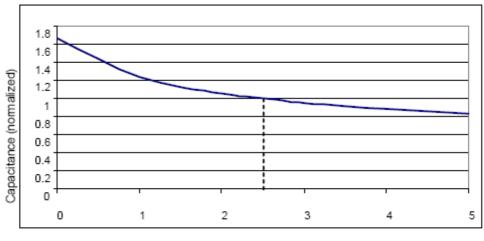


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND)

PERFORMANCE INFORMATION (Cont'd)

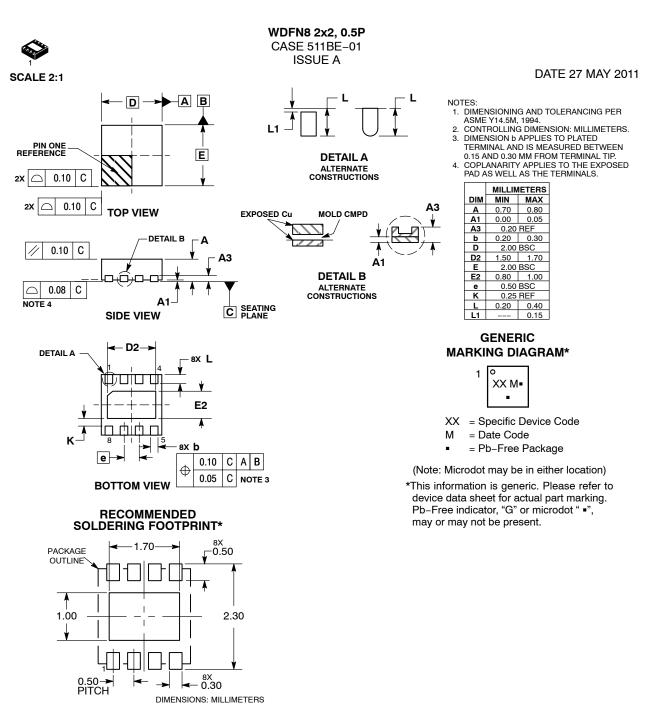
Typical Diode Capacitance vs. Input Voltage



DC Voltage

Figure 5. Filter Capacitance vs. Input Voltage (normalized to capacitance at 2.5 VDC and 25°C)





*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON48936E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	WDFN8, 2X2, 0.5P	PAGE 1 C		
ON Semiconductor reserves the right the suitability of its products for any pa	to make changes without further notice to an articular purpose, nor does ON Semiconducto	stries, LLC dba ON Semiconductor or its subsidiaries in the United States y products herein. ON Semiconductor makes no warranty, representation r assume any liability arising out of the application or use of any product or victorial damages. ON Semiconductor does not convey any license under	or guarantee regarding r circuit, and specifically	

rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales